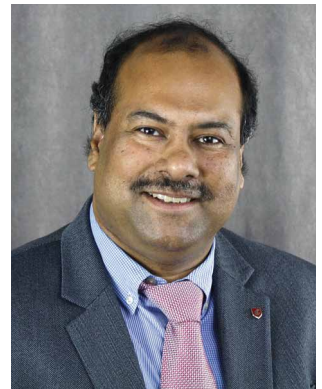


## From the EIC

# The 2023 Networks-on-Chip (NOCS) Symposium



■ **THE HIGHLIGHT OF** this issue is the journal-first model adopted for the articles accepted in the 17th edition of the Networks-on-Chip (NOCS) Symposium. NOCS is held in conjunction with the Embedded Systems Week (ESWEEK). This year, NOCS was held in Hamburg, Germany, on 21–22 September 2023, marking its return to a fully in-person symposium after virtual and hybrid editions during the pandemic. NOCS is the premier event dedicated to interdisciplinary research on on-chip, package-scale, chip-to-chip, and datacenter rack-scale communication technology as well as architectures, design methods, applications, and systems. NOCS brings together scientists and engi-

neers working on NoC innovations and applications from interdisciplinary research communities and areas, including discrete optimization and algorithms, computer architecture, networking, circuits and systems, packaging, embedded systems, and design automation. We thank the Technical Program Chairs of NOCS 2023, Masoumeh (Azin) Ebrahimi and Sujay Deb, along with the General Chairs Mahdi Nikdast and Miquel Moreto, for the timely delivery of all the accepted NOCS papers to the *IEEE Design&Test* submission system for further processing. This special issue consists of 15 papers.

I hope you enjoy reading this issue of *IEEE Design&Test*. ■

A handwritten signature in black ink, appearing to read 'P. Pande'.

**Partha Pratim Pande**, *Editor-in-Chief*  
Washington State University  
Pullman, WA 99164-2752 USA

Digital Object Identifier 10.1109/MDAT.2023.3316128  
Date of current version: 24 October 2023.